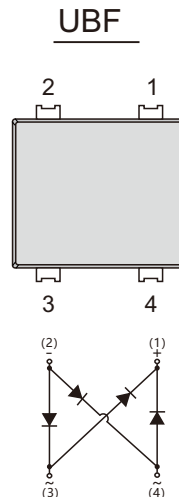


FEATURES

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Glass passivated chip junction
- Low Forward Voltage Drop
- Low Leakage Current
- Fast Reverse Recovery Time
- Component in accordance to RoHS 2015/863/EU

MECHANICAL DATA

- Case: UBF molded plastic body
- Terminals: Plated leads solderable per MIL-STD-750,method 2026
- Polarity:As Marked on body



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Rating at 25°C ambient temperature unless otherwise specified. Single phase ,half wave ,60Hz,resistive or inductive load. For capacitive load,derate current by 20%.)

Parameters	Symbols	UBF608	UBF610	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	800	1000	Volts
Maximum RMS Voltage	V_{RMS}	560	700	Volts
Maximum DC Blocking Voltage	V_{DC}	800	1000	Volts
Maximum Average Forward Rectified Current	$I_{(AV)}$	6.0		Amp
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	200		Amps
Rating for fusing (t<8.3ms)	I^2t	166		A^2s
Maximum Instantaneous Forward Voltage at 6 A	V_F	1.0		Volts
Maximum DC Reverse Current at rated DC blocking voltage	$T_A=25^{\circ}C$	5		μA
	$T_A=125^{\circ}C$	100		
Typical junction capacitance (Note2)	C_J	100		pF
Typical thermal resistance(Note1)	$R_{\theta JA}$	60		$^{\circ}C/W$
	$R_{\theta JC}$	10		
	$R_{\theta JL}$	12		
Operating junction and storage temperature range	T_J T_{STG}	-55 to +150		$^{\circ}C$

Note: 1.Mounted on glassepoxy Pcbboard with $4 \times 1.5'' \times 1.5''$ (3.81×3.81cm)copper pad.
2.Measured at 1MHZ and applied reverse voltage of 4.0 Volts.

RATINGS AND CHARACTERISTIC CURVES UBF608 THRU UBF610

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

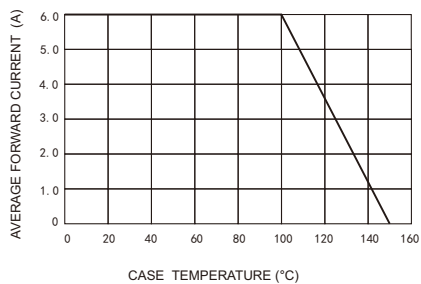


FIG.2-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

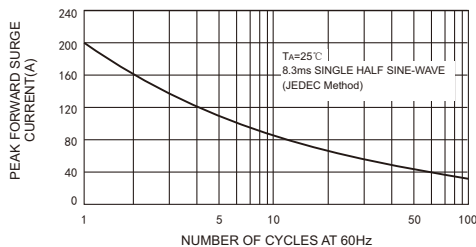


FIG.3-TYPICAL REVERSE CHARACTERISTICS

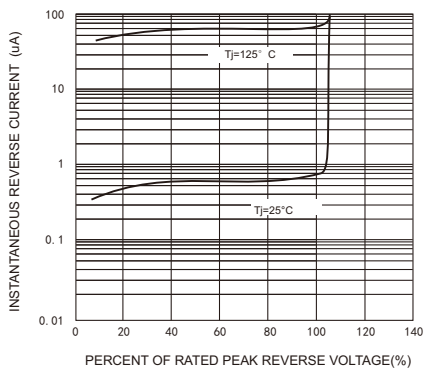


FIG.4-TYPICAL FORWARD CHARACTERISTICS

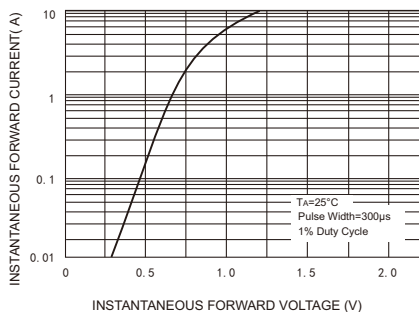
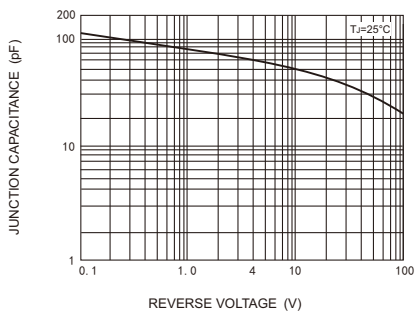


FIG.5-TYPICAL JUNCTION CAPACITANCE

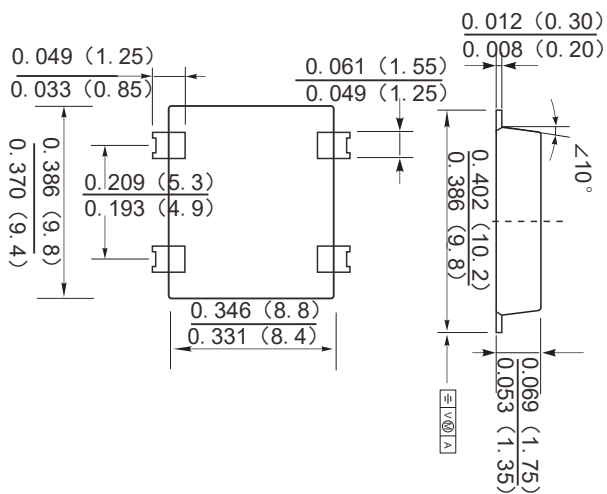


PACKAGE OUTLINE

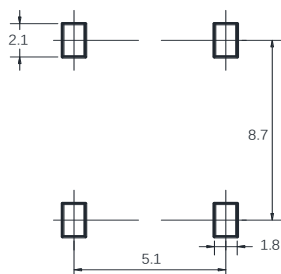
PACKAGE OUTLINE

UBF mechanical data

UBF



Suggested solder pad layout



Dimensions in millimeters

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